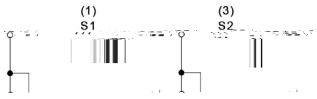
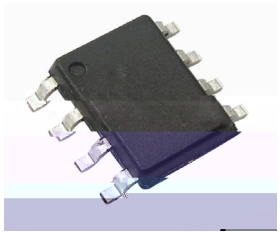
SOP-8 P MOS Dual P-Channel MOSFET in a SOP-8 Plastic Package.

Super high dense cell design for low $R_{DS(ON)}$,Rugged and reliable. HF Product.

Power Management in Notebook computer, Portable Equipment and Battery powered systems.





PIN1 S1 PIN 2 G1 PIN 3 S2 PIN 4 G2S(A)i

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DSS}	-20	V
Gate-Source Voltage	V_{GSS}	±12	V
Continuous Drain Current	I_D *	-3.0	A
Pulsed Drain Current	I_{DM}*	-12	A
Diode Continuous Forward Current	I_S*	-2.0	A
Power Dissipation for Single Operation	P_D* (Ta=25)	2	W
Power Dissipation for Single Operation	P_D* (Ta=100)	0.8	W
Maximum Junction Temperature	T_j	150	
Storage Temperature Range	T_{stg}	-55 150	
Thermal Resistance-Junction to Ambient	$R_{\theta JA}$*	62.5	/W

Note:

* Surface Mounted on 1in2 pad area, t ≤ 10sec.

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	BV_{DSS}	V_{GS}=0V I_{DS}=-250μA	-20			V

/ Electrical Characteristics(Ta=25)

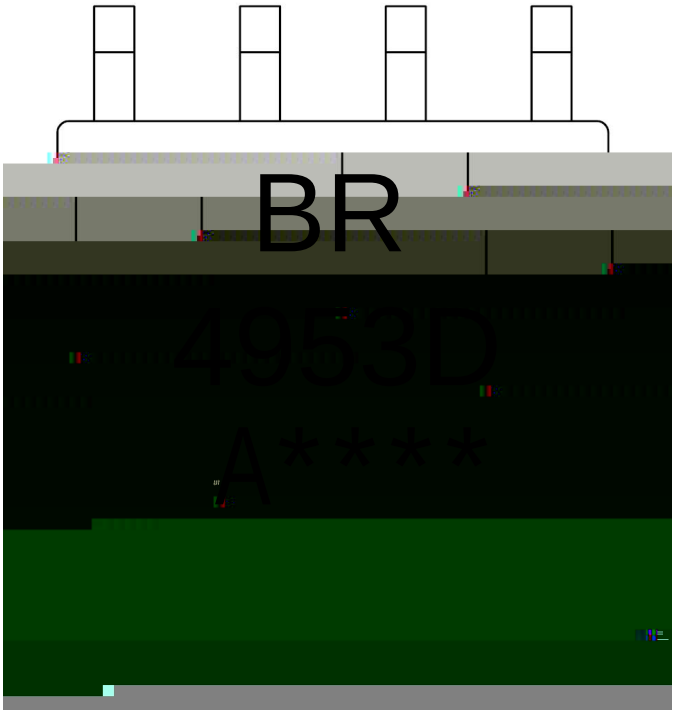
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Gate Resistance	R_G [b]	V_{GS}=0V V_{DS}=0V F=1MHz		6		Ω
Input Capacitance	C_{iss} [b]	V_{GS}=0V V_{DS}=-6V Frequency=1.0MHz		415		pF
Output Capacitance	C_{oss} [b]			223		
Reverse Transfer Capacitance	C_{rss} [b]			84		
Turn-on Delay Time	$t_{d(ON)}$ [b]	V_{DD}=-6V R_L=6Ω I_{DS}=-1A V_{GEN}=-10V R_G=6Ω		13	25	ns
Turn-on Rise Time	T_r [b]			36	60	
Turn-off Delay Time	$T_{d(OFF)}$ [b]			42	70	
Turn-off Fall Time	T_f [b]			34	60	

Notes:
a : Pulse test ; pulse width≤300μs, duty cycle≤2%.
b : Guaranteed by design, not subject to production testing.

/ Package Dimensions



/ Marking Instructions



BR

4953D

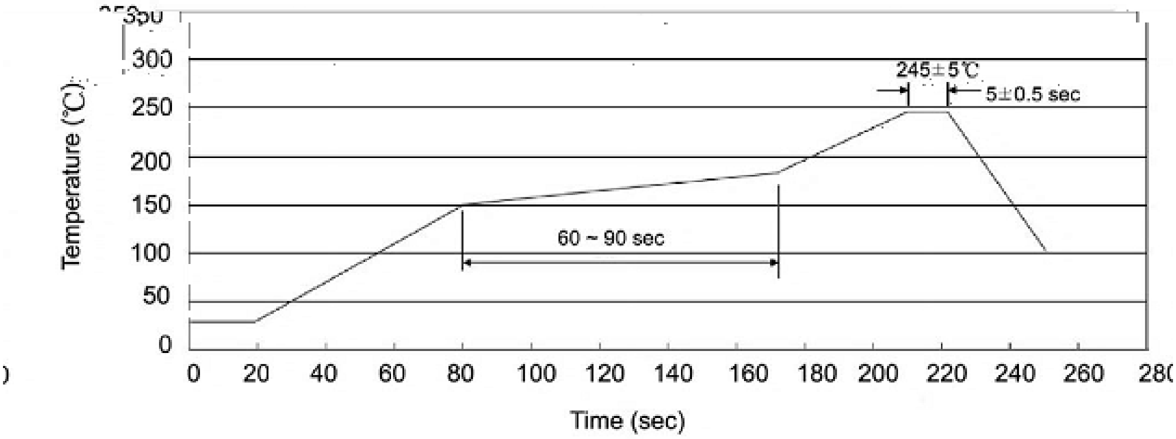
A: , A B C D……

****

Note:

BR:	Company Code.
4953D:	Product Type
A:	Chip sign(Flag bit may be empty,or the letter A B C D……).
****:	Lot No. Code, code change with Lot No.

( ) / Wh p shrdwxrh Prr iioh irr IU Uhiorw Vroghriq j+Pe-Frhh,



Note:

1 150 180 60 90sec;	1.Preheating:150~180 , Time:60~90sec.
2 245±5 5±0.5sec;	2.Peak Temp.:245±5 , Duration:5±0.5sec.
3 2 10 /sec.	3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

260±5	10±1 sec.	Temp.:260±5	Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type Units